



Product Change Notification - JAON-27SGKS288

Date:

03 Jan 2019

Product Category:

8-bit Microcontrollers

Affected CPNs:**Notification subject:**

CCB 3656, 3656.001 and 3656.002 Initial Notice: Qualification of GTK as a new assembly site for selected Atmel products of 35.5K wafer technology available in 24L SOIC package using palladium coated copper with gold flash (CuPdAu) bond wire.

Notification text:**PCN Status:**

Initial notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:

Qualification of GTK as a new assembly site for selected Atmel products of 35.5K wafer technology available in 24L SOIC package using palladium coated copper with gold flash (CuPdAu) bond wire.

Pre-Change:

Assembled at ANAP using palladium coated copper (PdCu) or palladium coated gold (AuPd) bond wire, 8290 die attach and G700LS or G600 mold compound material.

Post Change:

Assembled at GTK using palladium coated copper with gold flash (CuPdAu) bond wire, EN-4900GC die attach and G600F mold compound material.

Pre and Post Change Summary:

	Pre-Change		Post Change
Assembly Site	Amkor Technology Philippine (P1/P2), Inc. (ANAP)		Greatek Electronic Inc. (GTK)
Wire material	PdCu	AuPd	CuPdAu
Die attach material	8290		EN-4900GC
Molding compound material	G700LS	G600	G600F
Lead frame material	A194		A194

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve on-time delivery performance by qualifying GTK as a new assembly site.

Change Implementation Status:

In Progress

Estimated Qualification Completion Date:

April 2019

Note: Please be advised the qualification completion times may be extended because of unforeseen



business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

Workweek	January 2019					-->	April 2019				
	01	02	03	04	05		14	15	16	17	18
Initial PCN Issue Date	X										
Qual Report Availability								X			
Final PCN Issue Date								X			

Method to Identify Change:

Traceability code.

Qualification Plan:

Please open the attachments included with this PCN labeled as PCN_#_Qual Plan.

Revision History:

January 3, 2019: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

[PCN JAON-27SGKS288 Qual Plan.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

AT90PWM1-16SU
AT90PWM216-16SU
AT90PWM216-16SUR
AT90PWM2-16SQ
AT90PWM2-16SQR
AT90PWM2B-16SU
AT90PWM2B-16SUR